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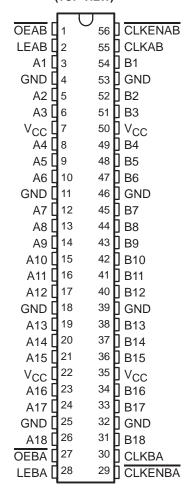
- Members of the Texas Instruments
   Widebus™ Family
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- UBT<sup>™</sup> (Universal Bus Transceiver)
   Combines D-Type Latches and D-Type
   Flip-Flops for Operation in Transparent,
   Latched, Clocked, or Clock-Enabled Mode
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V<sub>OLP</sub> (Output Ground Bounce)
   < 0.8 V at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C
- Flow-Through Architecture Optimizes PCB Layout
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

#### description

These 18-bit universal bus transceivers combine D-type latches and D-type flip-flops to allow data flow in transparent, latched, clocked, and clock-enabled modes.

Data flow in each direction is controlled by output-enable (OEAB and OEBA), latch-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs. The clock can be controlled by the clock-enable (CLKENAB and CLKENBA) inputs. For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if CLKAB is held at a high or low logic level. If LEAB is low, the A data is stored in the latch/flip-flop on the low-to-high transition of CLKAB. Output enable OEAB is active low. When OEAB is low, the outputs are active. When OEAB is high, the outputs are in the high-impedance state.

SN54ABT16601 . . . WD PACKAGE SN74ABT16601 . . . DGG OR DL PACKAGE (TOP VIEW)



Data flow for B to A is similar to that of A to B, but uses OEBA, LEBA, CLKBA, and CLKENBA.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16601 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16601 is characterized for operation from –40°C to 85°C.



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#### **FUNCTION TABLE**†

	I	NPUTS			OUTPUT
CLKENAB	OEAB	LEAB	CLKAB	Α	В
Х	Н	Х	Х	Χ	Z
Х	L	Н	Χ	L	L
Х	L	Н	Χ	Н	Н
Н	L	L	Χ	Χ	в <sub>0</sub> ‡
Н	L	L	Χ	Χ	в <sub>0</sub> ‡ в <sub>0</sub> ‡
L	L	L	$\uparrow$	L	L
L	L	L	$\uparrow$	Н	Н
L	L	L	L	Χ	B <sub>0</sub> ‡
L	L	L	Н	Χ	В <sub>0</sub> §

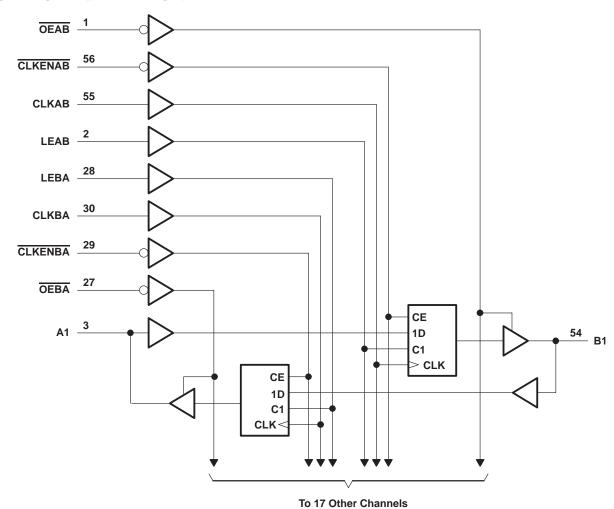
<sup>&</sup>lt;sup>†</sup> A-to-B data flow is shown: B-to-A flow is similar but uses <del>OEBA</del>, LEBA, CLKBA, and <del>CLKENBA</del>.



<sup>&</sup>lt;sup>‡</sup> Output level before the indicated steady-state input conditions were established

<sup>§</sup> Output level before the indicated steady-state input conditions were established, provided that CLKAB was low before LEAB went low

### logic diagram (positive logic)



# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	–0.5 V to 7 V
Input voltage range, V <sub>I</sub> (except I/O ports) (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, VO	0.5 V to 5.5 V
Current into any output in the low state, IO: SN54ABT16601	96 mA
SN74ABT16601	128 mA
Input clamp current, $I_{ K }(V_{ I } < 0)$	–18 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	–50 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2): DGG package	81°C/W
DL package	74°C/W
Storage temperature range, T <sub>stg</sub>	−65°C to 150°C
Output clamp current, $I_{OK}$ ( $V_O$ < 0)	–50 mA 81°C/W 74°C/W

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.



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### recommended operating conditions (see Note 3)

			SN54AB1	Г16601	SN74AB1	16601	UNIT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	V <sub>IH</sub> High-level input voltage				2		V
VIL	L Low-level input voltage					0.8	V
٧ <sub>I</sub>	Input voltage		0	VCC	0	VCC	V
ЮН	High-level output current			-24		-32	mA
loL	Low-level output current			48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
TA	Operating free-air temperature		<b>–</b> 55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		Т	A = 25°C	;	SN54ABT16601		SN74ABT16601		UNIT
PAI	RAMETER	TEST CONDITIONS		MIN	TYP <sup>†</sup>	MAX	MIN	MAX	MIN	MAX	UNIT
VIK		$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2		-1.2		-1.2	V
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5		
\ \/ a · ·		V <sub>CC</sub> = 5 V,	$I_{OH} = -3 \text{ mA}$	3			3		3		V
VOH		V <sub>CC</sub> = 4.5 V	$I_{OH} = -24 \text{ mA}$	2			2				V
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*					2		
VOL		V <sub>CC</sub> = 4.5 V	$I_{OL} = 48 \text{ mA}$			0.55		0.55			V
VOL		VCC = 4.5 V	$I_{OL} = 64 \text{ mA}$			0.55*				0.55	V
V <sub>hys</sub>	_				100						mV
1.	Control inputs	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = V <sub>CC</sub> or GND			±1		±1		±1	μΑ
li .	A or B ports	VCC = 3.5 V,	1 = 100 01 011D			±20**		±100		±20	μΑ
l <sub>off</sub>		$V_{CC} = 0$ ,	$V_I$ or $V_O \le 4.5 \text{ V}$			±100				±100	μΑ
ICEX		V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 5.5 V	Outputs high			50		50		50	μА
IO <sup>‡</sup>		$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA
IOZH§		$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 2.7 V			10		10		10	μΑ
I <sub>OZL</sub> §		$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 0.5 V			-10		-10		-10	μΑ
		V <sub>CC</sub> = 5.5 V,	Outputs high		1.9	3		2		3	
Icc	$I_{CC}$ A or B ports $I_{O} = 0$ ,	$I_{O} = 0$ ,	Outputs low		28	36		35		36	mA
		$V_I = V_{CC}$ or GND	Outputs disabled		1.6	3		2		3	
A. ¶		V <sub>CC</sub> = 5.5 V, One i	nput at 3.4 V,			50				50	μΑ
∆lcc¶		Other inputs at V <sub>CC</sub> or GND						1.5			mA
Ci	Control inputs	$V_{ } = 2.5 \text{ V or } 0.5 \text{ V}$			3						pF
C <sub>io</sub>	A or B ports	$V_0 = 2.5 \text{ V or } 0.5 \text{ V}$	/		9						pF

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter does not apply.



<sup>\*\*</sup> This limit applies only to the SN74ABT16601.

<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ .

<sup>‡</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

<sup>§</sup> The parameters I<sub>OZH</sub> and I<sub>OZL</sub> include the input leakage current.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than V<sub>CC</sub> or GND.

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# timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

				SN54AB	Г16601	SN74AB1	Г16601	UNIT
				MIN	MAX	MIN	MAX	UNIT
fclock	Clock frequency			0	150	0	150	MHz
		LEAB or LEBA high		2.5		2.5		ns
t <sub>W</sub>	Puise duration	CLKAB or CLKBA high or low	AB or CLKBA high or low			3		115
		A before CLKAB↑ or B before CLKBA↑		4.6		4		
۱.	Cotup time	A before LEAB↓ or B before LEBA↓	CLK high	2.5		2.5		20
t <sub>su</sub>	Setup time	CLK low		1.3		1		ns
		CLKEN before CLK↑	2.9		2.5			
		A after CLKAB↑ or B after CLKBA↑		0.4		0		
th	Hold time	A after LEAB↓ or B after LEBA↓	2.8		2		ns	
		CLKEN after CLK↑	0		0			

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
f <sub>max</sub>			150	200		150		MHz
t <sub>PLH</sub>	A or B	B or A	1.5	2.5	4.1	1	4.6	—l ns l
<sup>t</sup> PHL	AOIB	BULK	1.5	3.4	4.7	1	5.1	
tPLH	LEAB or LEBA	B or A	2	3.4	4.7	1	5.6	ns
t <sub>PHL</sub>	LLAD OF LLDA	BUIA	2	3.7	5	1	5.5	113
t <sub>PLH</sub>	CLKAB or CLKBA	B or A	1.5	3.2	4.5	1	5.2	ns
t <sub>PHL</sub>	CLNAD OF CLNDA	BULK	1.5	3.2	4.4	1	5	115
<sup>t</sup> PZH	<u> </u>	B or A	2	4	5	1	5.7	
t <sub>PZL</sub>	OEAB or OEBA	BULK	2	4.2	5.6	1	6	ns
<sup>t</sup> PHZ	OEAB or OEBA	B or A	2	4.5	5.8	1	6.8	ns
t <sub>PLZ</sub>	OEAR OF OERA	BULK	1.5	3.4	5.3	1	6.3	1115

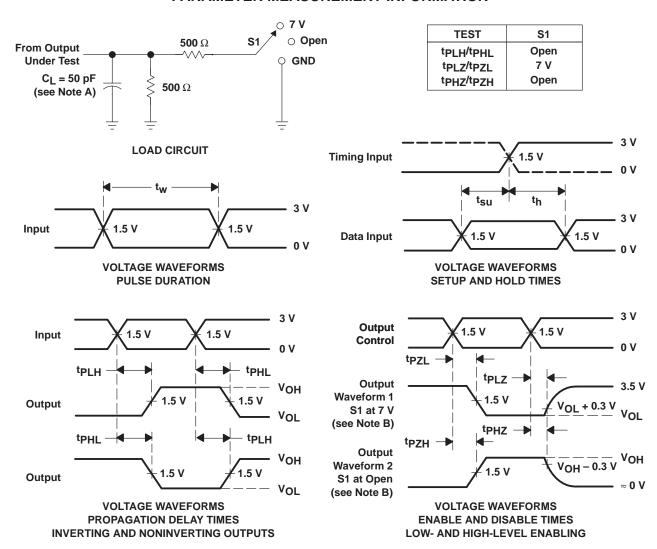
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switching characteristics over recommended ranges of supply voltage and operating free-air temperature,  $C_L$  = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5 V$ , $T_A = 25^{\circ}C$			MIN	MAX	UNIT
			MIN	TYP	MAX			
f <sub>max</sub>			150	200		150		MHz
<sup>t</sup> PLH	A or B	B or A	1.5	2.5	3.6	1.5	4	
<sup>t</sup> PHL	AUIB	BUIA	1.5	3.4	4.7	1.5	4.9	ns
<sup>t</sup> PLH	LEAB or LEBA	B or A	2	3.4	4.7	2	5	ns
<sup>t</sup> PHL	LEAD OF LEDA	BUIA	2	3.7	5	2	5.2	
<sup>t</sup> PLH	CLKAB or CLKBA	B or A	1.5	3.2	4.5	1.5 4.7	no	
<sup>t</sup> PHL	CLNAD OF CLNDA	BUIA	1.5	3.2	4.4	1.5	4.6	4.6 ns
<sup>t</sup> PZH		B or A	2	4	5	2	5.5	no
t <sub>PZL</sub>	OEAB or OEBA	D OF A	2	4.2	5.6	2	5.8	ns
<sup>t</sup> PHZ	OFAR as OFRA	B or A	2	4.5	5.4	2	6.2	ne
tPLZ	OEAB or OEBA	BULA	1.5	3.4	4.7	1.5	5.4	ns 5.4



#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50~\Omega$ ,  $t_f \leq$  2.5 ns,  $t_f \leq$  2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





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#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	n MSL Peak Temp <sup>(3)</sup>
5962-9467101QXA	ACTIVE	CFP	WD	56	1	None	Call TI	Level-NC-NC-NC
SN74ABT16601DGGR	ACTIVE	TSSOP	DGG	56	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74ABT16601DL	ACTIVE	SSOP	DL	56	20	None	CU NIPDAU	Level-1-235C-UNLIM
SN74ABT16601DLR	ACTIVE	SSOP	DL	56	1000	None	CU NIPDAU	Level-1-235C-UNLIM
SNJ54ABT16601WD	ACTIVE	CFP	WD	56	1	None	Call TI	Level-NC-NC-NC

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

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Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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